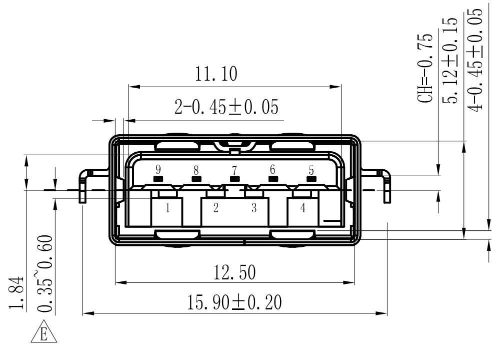
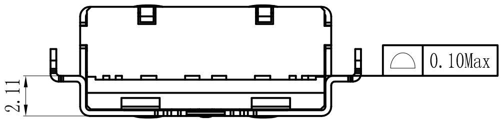
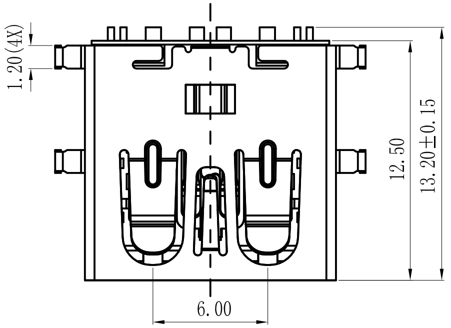
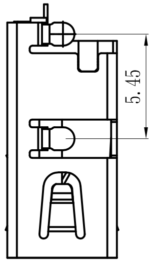
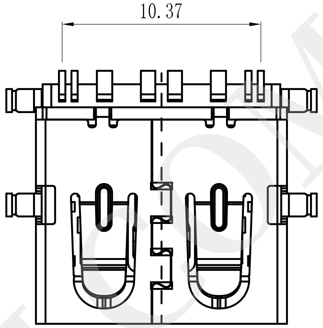










NOTE:

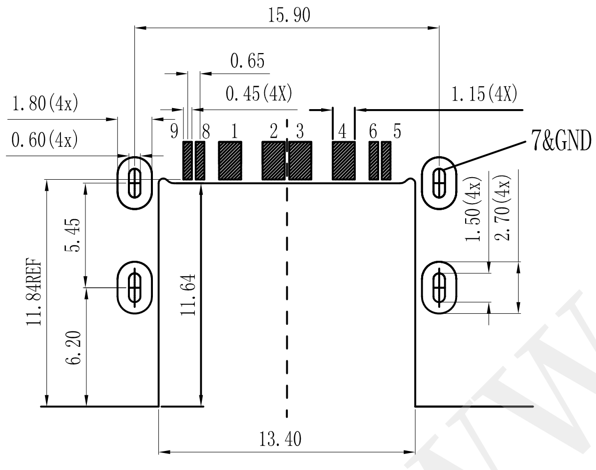
1.MATERIAL:
1.1 INSULATOR:LCP+30%GF, UL94 V-0.
1.2 CONTACT 1~4PIN: C5191-EH.
1.3 CONTACT 5~9PIN: C5191-EH.
1.4 SHELL: SUS304 3/4H

2. PLATING:
2.1 CONTACT:
CONTACT AREA: GOLD PLATING.
SOLDER AREA: 100u" Min MATTE TIN PLATING.
UNDER PLATE: 50u" Min NICKEL PLATING.
2.2 SHELL:50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:
3.1 ELECTRICAL CHARACTERISTICS;
CONTACTRESISTANCE:30mΩ MAXIMUM
CONTACT CURRENT RATING: 3A
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.
INSULATION RESISTANCE: 100 MEGOHMS MIN
OPERATING TEMPEROTURE: -25° C ～ +85° C
3.2 MECHANICAL:
MATING FORCE: 8N-20N.
UNMATING FORCE: 8N-20N.

4.PART MUST COMPLY ROHS SPECIFICATION

5.WAVE SOLDER:THE CONNECTOR SHALL BE MOUNENTD ON THE PCB.THE TEMPERATURE OF THE SOLDER SHALL BE 260±5 ° C AND IMMERSION DURATION 5 SECONDS.



TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT

(TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

NO.	PART NAME	MATERIAL	DESCRIPTION
3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	C5191-EH	Overall nickel plating 50U "~ 100u", contact area gold plating 1U ", welding leg tin plating 100u"
1	HSG	LCP+30%GF	BLACK/BLUE UL94V-0

HOAUC

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.1 AF 10Gbps 沉板 H=2.11mm
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC183-USBA09-211
UNIT: mm [inch]			MOLD NO.
	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2604281533
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1